

USB-Compliant Single-cell Li-lon Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: 0.5% at 25°C 1% from 0 to 125°C
- ±6% Input Current Regulation Accuracy
- ±4% Charge Current Regulation Accuracy
- 26V Absolute Maximum Input Voltage
- 6V Maximum Input Operating Voltage
- 2A Charge Rate
- Programmable through High-Speed I²C
 Interface(3.4Mb/s) with Fast Mode Plus
 Compatibility
 - Input Current
 - Fast-Charge/Termination Current
 - Charger Voltage
 - Recharge Voltage
 - Termination Enable
- 1.5MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1µH External Inductor
- Dynamic Input Voltage Control
- Low Reverse Leakage to Prevent Battery Drain to VBUS
- 5V, 1A Boost Mode for USB OTG for 3.2V to 4.5V Battery Input
- Available in DFN3*3-12 Packages.

Descriptions

The DIO59020 combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery.

The charging parameters and operating modes are programmable through an I²C Interface that operates up to 3.4Mbps. The charger regulator circuits switch at 1.5MHz to minimize the size of external passive components.

The DIO59020 provides battery charging in thr ee phases: pre-charge, constant current and c onstant voltage.

To ensure USB compliance and minimize charging time, the input current limit can be changed through the I²C by the host processor. Charge termination is determined by a programmable minimum current level.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, preventing leakage from the battery to the input. Charge current is reduced when the die temperature reaches 120°C, protecting the device and PCB from damage.

The DIO59020 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery and uses the same external components used for charging the battery.

Applications

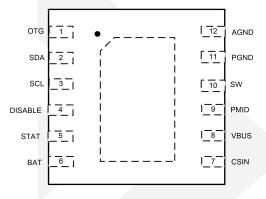
- Cell Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras



Ordering Information

Order Part Number	Top Marking		T _A	Package	
DIO59020CD12	59020	Green	-40 to 85°C	DFN3*3-12	Tape & Reel, 5000

Pin Assignments



DFN3*3-12

Figure 1. Pin Assignment (Top View)

Pin Definitions

Name	Description				
VBUS	Charger Input Voltage and USB-OTG output voltage. Bypass with a 1µF capacitor to PGND.				
NC	No Connect. No external connection is made between this pin and the IC's internal circuitry.				
SCL	I ² C Interface Serial Clock. This pin should not be left floating.				
PMID	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 10μF, 6.3V capacitor to PGND.				
SDA	I ² C Interface Serial Data. This pin should not be left floating.				
SW	Switching Node. Connect to output inductor.				
STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charging.				
PGND	Power Ground. Power return for gate drive and power transistors. The connection from this pin to the bottom of CMID should be as short as possible.				
OTG	On-The-Go. Enables boost regulator in conjunction with OTG_EN and OTG_PL bits (see Table 13).				
CSIN	Charging current detection input terminal.				
DISABLE	Charge Disable. If this pin is HIGH, charging is disabled. When LOW, charging is controlled by the I ² C registers.				
BAT	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1µF capacitor to PGND if the battery is connected through long leads.				
AGND	Analog ground.				



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

	Parameter	Rating	Unit
VPLIS Voltago	Continuous	-1.4 to 26.0	V
VBUS Voltage	Pulsed, 100ms Maximum Non-Repetitive	-2.0 to 26.0	V
STAT Voltage		-0.3 to 26.0	V
PMID Voltage		6.5	V
SW, CSIN, VBAT, DISABLE V	oltage	-0.3 to 6.5	V
Voltage on Other Pins		-0.3 to 6.5	V
Maximum V _{BUS} Slope above 5	.5V when Boost or Charger are Active	4	V/µs
Junction Temperature		-40 to 150	°C
Storage Temperature		-65 to 150	°C
Lead Soldering Temperature,	10 Seconds	260	°C

Recommend Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating conditions are specified to ensure optimal performance to the datasheet specifications. DIOO does not Recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter	Rating	Unit	
Supply Voltage		4 to 6	V
Maximum Battery Voltage when Boost enabled		4.5	V
Negative VBUS Slew Rate during VBUS Short	T _A ≤60°C	4	V/µs
Circuit, C _{MID} ≤4.7μF	T _A ≥60°C	2	ν/μ5
Ambient Temperature		-30 to 85	°C
Junction Temperature		-30 to 120	°C



Electrical Characteristics

 V_{IN} = 5V, T_A = 25°C, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni	
Power Supp	olies						
		V _{BUS} >V _{BUS(min)} , PWM Switching		10		mA	
I _{VBUS}	VBUS Current	V _{BUS} > V _{BUS(min)} ; PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100 mA		0.2		mA	
		0°C <tj<85°c, hz_mode="1</td"><td></td><td>96</td><td></td><td>μA</td></tj<85°c,>		96		μA	
I _{LKG}	VBAT to VBUS Leakage Current	0°C <tj<85°c, hz_mode="1,<br">VBAT=4.2V, VBUS=0V</tj<85°c,>		1.6	5.0	μA	
Battery is charge Current in High- Impedance Mode		0°C <tj< 85°c,="" hz_mode="1,<br">VBAT=4.2V</tj<>		12	20	μΑ	
		DISABLE=1, 0°C <tj<85°c, VBAT=4.2V</tj<85°c, 		12	20	μ	
Charger Vo	oltage Regulation						
	Charge Voltage Range		4.2		4.4	V	
V_{OREG}	Chargo Voltago Acquirocy	T _A =25°C	-0.5%		0.5%		
	Charge Voltage Accuracy	TJ=0 to 125°C	-1%		1%		
Charging C	Surrent Regulation						
	Output Charge Corrent Dance	$V_{SHORT} < V_{BAT} < V_{OREG},$ $R_{SENSE} = 68 \text{m}\Omega$	550		1500		
I _{OCHRG}	Output Charge Current Range	$V_{SHORT} < V_{BAT} < V_{OREG},$ $R_{SENSE} = 51 \text{m}\Omega$	735		1996	m <i>F</i>	
	Charge Current Accuracy Across	20mV ≤ V _{IREG} ≤ 40mV	-6		6	%	
	R _{SENSE}	V _{IREG} >40mV	-4		4	%	
Logic Leve	Is: DISABLE, SDA, SCL, OTG						
			1.05			V	
V _{IH}	High-Level Input Voltage		1.03		Δ.		
V _{IH}	High-Level Input Voltage Low-Level Input Voltage		1.03		0.4	V	
		Input Tied to GND or V _{IN}	1.03	0.01	0.4		
V _{IL}	Low-Level Input Voltage	Input Tied to GND or V _{IN}	1.03	0.01			
V _{IL}	Low-Level Input Voltage Input Bias Current	Input Tied to GND or V_{IN} $V_{BAT} > V_{OREG} - V_{RCH}, R_{SENSE} = 68 m\Omega$	46	0.01		μA	
V _{IL}	Low-Level Input Voltage Input Bias Current mination Detection Termination Current Range			0.01	1.00	μ <i>A</i>	
V _{IL}	Low-Level Input Voltage Input Bias Current mination Detection	V_{BAT} > V_{OREG} - V_{RCH} , R_{SENSE} = $68m\Omega$	46	0.01	1.00	V μA mA %	

4



		DIO59020				
Input Power	r Source Detection					
V _{IN(MIN)}	VBUS Input Voltage Rising	To Initiate and Pass VBUS Validation	3.75	4	4.25	V
V_{hys}				0.3		V
t _{VBUS_VALID}	VBUS Validation Time			30		ms
Special Cha	arger (V _{BUS})		•			1
V_{SP}	Special Charger Set point Accuracy		-3		3	%
Input Curre	nt Limit		1			1
		REG[7:6]=00		100		
	land Coment limit The sheld	REG[7:6]=01	470	500	530	
I _{INLIM}	Input Current Limit Threshold	REG[7:6]=10	750	800	850	mA
		REG[7:6]=11		No limit		
Battery Rec	harge Threshold					
	Recharge Threshold	Below V _(OREG)	50		200	mV
V_{RCH}	Deglitch Time	V _{BAT} Falling Below V _{RCH} Threshold		30		ms
STAT Outpu	ıt					1
V _{STAT(OL)}	STAT Output Low	I _{STAT} =10mA			0.4	V
ISTAT(OH)	STAT High Leakage Current	V _{STAT} =5V			1	μA
Sleep Comp	parator					
V _{SLP}	Sleep-Mode Entry Threshold, V _{BUS} - V _{BAT}	4V≤V _{BAT} ≤V _{OREG} , V _{BUS} Falling	0	0.04	0.1	V
V _{SLP-EXIT}	Sleep-Mode Exit Threshold, V_{BUS} - V_{BAT}			0.1		V
t _{SLP_EXIT}	Deglitch Time for VBUS Rising Above V _{BAT} by V _{SLP}	Rising Voltage		30		ms
Power Swite	ches					1
4	Q3 On Resistance(VBUS to PMID)	I _{IN(LIMIT)} =500mA		86		
R _{DS(ON)}	Q1 On Resistance(PMID to SW)			85		mΩ
	Q2 On Resistance(SW to GND)			75		
Charger PW	/M Modulator					•
f _{SW}	Oscillator Frequency			1.5		MHz
D _{MAX}	Maximum Duty Cycle				100	%
D _{MIN}	Minimum Duty Cycle			6		%
I _{SYNC}	Synchronous to Non-Synchronous Current Cut-Off Threshold	Low-Side MOSFET(Q2) Cycle-by- Cycle Current Limit		300		mA



		DIO59020				
Boost Mode	e Operation(OPA_MODE=1, HZ_MC	ODE=0)				
.,		$2.5V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to 200 mA	4.85	5.05	5.2	
V _{BOOST}	Boost Output Voltage at VBUS	3.0V < V _{BAT} <4.5V, I _{LOAD} from 0 to 500mA	4.8	5.05	5.2	V
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{BAT} =3.6V, I _{OUT} =0		500		μA
I _{LIMPK(BST)}	Q2 Valley Current Limit			2.5		А
1840	Minimum Battery Voltage for Boost	While Boost Active		2.6		V
UVLO _{BST}	Operation	To Start Boost Regulator		2.7		V
Battery Dete	ection					
I _{DETECT}	Battery Detection Sink Current	Begins after Charge Termination Detected		10		mA
t _{DETECT}	Battery Detection Time			30		ms
Protection a	and Timers					
VBUS _{OVP}	VBUS Over-Voltage Shutdown	V _{BUS} Rising	5.82	6	6.2	V
VBU30VP	Hysteresis	V _{BUS} Falling		200		m∨
I _{LIMPK(CHG)}	Q1 Cycle-by-Cycle Peak Current Limit	Charge Mode		3.4		А
	Battery Short-Circuit Threshold	V _{BAT} Rising	1.95	2	2.05	V
V _{SHORT}	Hysteresis	V _{BAT} Falling		100		mV
I _{SHORT}	Linear Charging Current	V _{BAT} <v<sub>SHORT</v<sub>	20	30	40	mA
т	Thermal Shutdown Threshold	T _J Rising		145		- °c
T _{SHUTDWN}	Hysteresis	T _J Falling		10		
T _{CF}	Thermal Regulation Threshold	Charge Current Reduction Begins		120		°C
t _{INT}	Detection Interval			30		ms



I²C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Un	
		Standard Mode			100		
£	COL OL- I. F wenny	Fast Mode			400		
f _{SCL}	SCL Clock Frequency	High-Speed Mode, C _B ≤100pF			3400	kH	
		High-Speed Mode, C _B ≤400pF			1700	1	
4	Bus-Free Time between STOP	Standard Mode		4.7		116	
t _{BUF}	and START Conditions	Fast Mode		1.3		μs	
	CTART OR COLOR OTART	Standard Mode		4		μ	
$t_{\text{HD;STA}}$	START or Repeated START Hold Time	Fast Mode	s	600		ns	
	Hold Time	High-Speed Mode		160		ns	
		Standard Mode		4.7		μ	
t _{LOW}	COLLOW Paried	Fast Mode		1.3		μ	
	SCL LOW Period	High-Speed Mode, C _B ≤100pF		160		n	
		High-Speed Mode, C _B ≤400pF		320		n	
tнісн		Standard Mode		4		μ	
	SCL HIGH Period	Fast Mode		600		n	
		High-Speed Mode, C _B ≤100pF		60		n	
		High-Speed Mode, C _B ≤400pF		120		n	
		Standard Mode		4.7		μ	
t _{SU;STA}	Repeated START Setup Time	Fast Mode		600		n	
		High-Speed Mode		160		n	
		Standard Mode		250			
t _{SU;DAT}	Data Setup Time	Fast Mode		100		n	
		High-Speed Mode		20			
		Standard Mode	0		3.45	μ	
t _{HD;DAT}	Data Hold Time	Fast Mode	0		900	n	
CHD;DAT	Data Hold Time	High-Speed Mode, C _B ≤100pF	0		70	n	
		High-Speed Mode, C _B ≤400pF	0		150	n	
		Standard Mode	20+	0.1C _B	100		
too	SCL Rise Time	Fast Mode	20+	0.1C _B	300	l n	
t _{RCL}	SOL Mise Time	High-Speed Mode, C _B ≤100pF		10	80	ns	
		High-Speed Mode, C _B ≤400pF		20	160		
		Standard Mode	20+	0.1C _B	300		
t_{FCL}	SCL Fall Time	Fast Mode	20+	0.1C _B	300] ns	
		High-Speed Mode, C _B ≤100pF		10	40		



		High-Speed Mode, C _B ≤400pF		20	80	
	SDA Rise Time	Standard Mode	20+	0.1C _B	300	
t _{RDA}	Rise Time of SCL after a	Fast Mode	20+	0.1C _B	300	
t _{RCL1}	Repeated START Condition and	High-Speed Mode, C _B ≤100pF		10	80	ns
	after ACK Bit	High-Speed Mode, C _B ≤400pF		20	160	
	SDA Fall Time	Standard Mode	20+0.1C _B		300	
		Fast Mode	20+0.1C _B		300	
t _{FDA}		High-Speed Mode, C _B ≤100pF		10	80	ns
		High-Speed Mode, C _B ≤400pF		20	160	
		Standard Mode		4		μs
t _{su;sto}	Stop Condition Setup Time	Fast Mode		600		ns
		High-Speed Mode		160		ns
Св	Capacitive Load for SDA, SCL				400	pF

Timing Diagrams

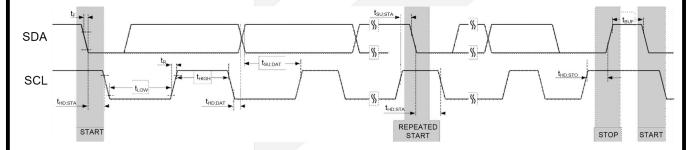
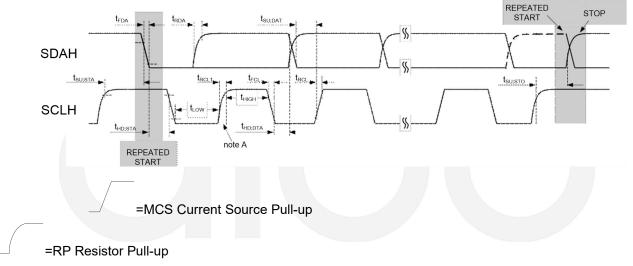


Figure 2. I²C Interface Timing for Fast and Slow Modes



Note A: First rising edge of SCH after Repeated Start and after each ACK bit.

Figure 3. I²C Interface Timing for High-Speed Mode



Typical Application

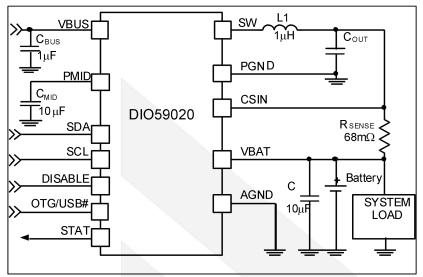


Figure 4. Typical Application

Block Diagram

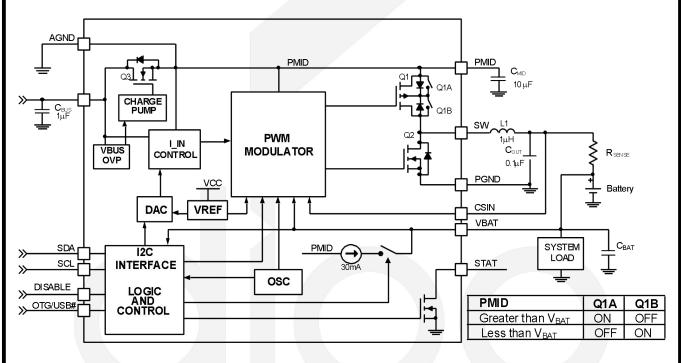


Figure 5. IC and System Block Diagram



Application Information

Circuit Description/Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

DIO59020 combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The DIO59020 has three operating modes:

- 1. Charge Mode:
 - Charge a signal-cell Li-ion or Li-polymer battery.
- 2. Boost Mode:
 - Provide 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.
- 3. High-Impedance Mode:
 - Both the boost and charging circuits are OFF in this mode. Current flow from VBUS to the battery or from the battery to VBU is blocked in this mode. This mode consumes very little current from VBUS or the battery.

Note: Default setting is denoted bold typeface.

Charge Mode

In charge Mode, DIO59020 employs four regulation loops:

- 1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.
- Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
- 3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage roses the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
- 4. Temperature: If the IC's junction temperature reaches 120°C,charge current is reduced until the IC's temperature stabilizes at 120°C.
- An additional loop limits the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

Battery Charging Curve

If the battery voltage is below V_{SHORT} , a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT} . The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The DIO59020 is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the current available to charge the battery and power the system. The effect of I_{INLIM} on I_{CHARGE} can be seen in Figure 7.



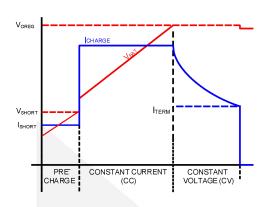


Figure 6. Charge Curve, ICHARGE Not Limited by IINLIM

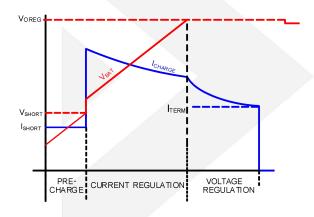


Figure 7. Charge Curve, I_{INLIM} Limits I_{CHARGE}

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit (REG[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.2V to 4.4V, as shown in Table 1.

Table 1. OREG Bits (OREG[7:2]) vs. Charge Vout (Voreg) Float Voltage

Decimal	Hex	V _{OREG}
0~35	00~23	4.20
36~40	24~28	4.30
41~43	29~2B	4.35
44~62	2C~3E	4.40

The following charging parameters can be programmed by the host through I²C.

Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V _{OREG}	REG2[7:2]
Battery Charging Current Limit	I _{OCHRG}	REG4[6:4]
Input Current Limit	I _{INLIM}	REG1[7:6]
Charge Termination Limit	I _{TERM}	REG4[2:0]



A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG}-V_{RCH}
- VBUS Power on Reset (POR) clears and the battery voltage is below the V_{SHORT}.
- CE or HZ MODE is rest through I²C write to CONTROL1 (Reg1) register.

Charge Current Limit (Iocharge)

Table 3. IOCHARGE (REG4 [6:4]) Current as Function of IOCHARGE Bits and RSENSE Resistor Values

DEC	BIN	HEX	V _{RSENSE}	Iochard	GE (mA)
DEC	DIN	ПЕХ	(mV)	51mΩ	68mΩ
0	000	00	37.5	735	551
1	001	01	44.4	870	653
2	010	02	51.2	1004	753
3	011	03	57.5	1127	846
4	100	04	71.3	1398	1048
5	101	05	78.1	1531	1149
6	110	06	91.9	1802	1351
7	111	07	101.8	1996	1498

Table 4. V_{RCH} (REG7 [1:0]) Recharge Voltage

	111111		
DEC	BIN	HEX	V _{RCH} (mV)
0	00	00	50
1	01	01	100
2	10	02	150
3	11	03	200

Termination Current Limit

Current charge termination is enabled when TE (REG1[3]) =1. Typical termination current values are given in Table 5.

Table 5. ITERM Current as Function of ITERM Bits (REG4[2:0]) and RSENSE Resistor Values

I	V _{RSENSE}	I _{TERM} (mA)				
I _{TERM}	(mV)	51mΩ	68mΩ			
0	3.1	61	46			
1	6.3	124	92			
2	9.4	184	138			
3	12.5	245	184			
4	15.6	306	230			
5	18.8	369	276			
6	21.9	429	322			
7	25	490	368			

When the charge current falls below I_{TERM}, PWM charging stops and the STAT bits change to READY (00) for about 30ms while the IC determines whether the battery and charging source are still connected. STAT then changes to CHARGE DONE (10), provided the battery and charger are still connected.



PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulator the output voltage and battery charge currents. The synchronous rectifier (Q2) has a current limit that which off the FET when the current is negative by more than 300mA peak. This prevents current flow from battery.

V_{BUS} POR/Non-Compliant Charger Rejection

When the IC detects that VBUS has risen above $V_{IN(MIN)}$ (4.3V), the IC applies a 250 Ω load from VBUS to GND. To clear the VBUS POR (Power-On-Reset) and begin charging, VBUS must remain above $V_{IN(MIN)}$ and below VBUS_{OVP} for t_{VBUS_VALID} (30ms) before the IC initiates Charging. The VBUS validation sequence always occurs charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation).

tvbus_valid ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

Table 6. Input Current Limit

I _{INLIM} REG[7:6]	Input Current Limit
00	100 mA
01	500 mA
10	800 mA
11	No limit

Flow Charts

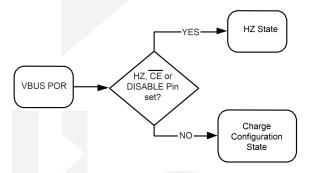


Figure 8. Charger VBUS POR



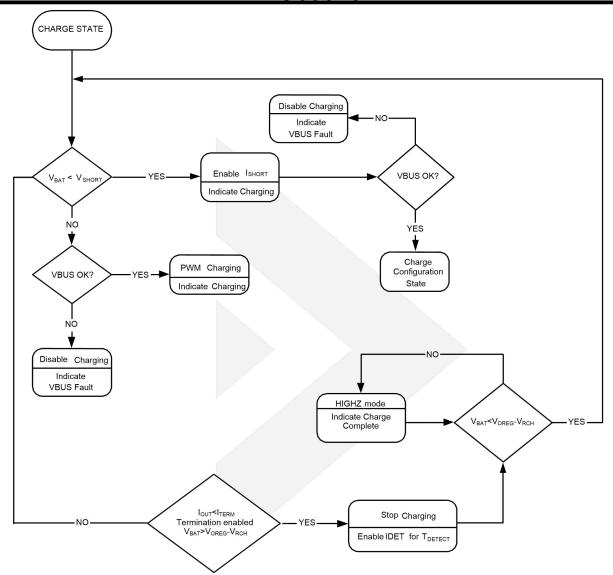


Figure 9. Charge Mode

Special Charger

The DIO59020 has additional functionality to limit input current in case a current-limited "special charger" is supplying VBUS. These slowly increase the charging current until either.

I_{INLIM} or I_{OCHARGE} is reached

or

■ V_{BUS}=V_{SP}.

If V_{BUS} collapses to V_{SP} when the current is ramping up, the DIO59020 charge with an input current that keeps V_{BUS} = V_{SP} . When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set.



Table 7. V_{SP} as Function of SP Bits (REG5[2:0])

DEC	BIN	HEX	V _{SP}
0	000	00	4.225
1	001	01	4.300
2	010	02	4.375
3	011	03	4.450
4	100	04	4.525
5	101	05	4.600
6	110	06	4.675
7	111	07	4.750

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120°C), the charger reduces its output current to prevent overheating. If the temperature increases beyond T_{SHUTDOWN}; charging is suspended, the FAULT bits are set to 101, and STAT is pulsed HIGH. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes at programmed current after the die cools to about 120°C.

Charge Mode Input Supply Protection

Sleep Mode

When V_{BUS} falls below $V_{BAT}+V_{SLP}$ and V_{BUS} is above $V_{IN(MIN)}$, the IC enters Sleep Mode to prevent the battery from draining into VBUS. During Sleep Mode, reverse current is disabled by body switching Q1.

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below V_{IN(MIN)}, the IC:

- Terminates charging.
- 2. Pulses the STAT pin, sets the STAT bits to 11, and sets the FAULT bits to 011.

If V_{BUS} recovers above the $V_{IN(MIN)}$ rising threshold after time t_{INT} (about two seconds), the charging process is repeated. This function prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or a low-current-capable OTG device.

Input Over-Voltage Detection

When the V_{BUS} exceeds VBUS_{OVP}, the IC:

- 1. Turns off Q3
- 2. Suspends charging
- 3. Sets the FAULT bits to 001, sets the STAT bits to 11, and pulses the STAT pin.

When V_{BUS} falls about 200mV below VBUS_{OVP}, the fault is cleared and charging resumes after V_{BUS} is revalidated (see VBUS POR/Non-Compliant Charger Rejection).

VBUS Short While Charging

If VBUS is shorted with a very low impedance while the IC is charging with II_{NLIMIT}=100mA, the IC may not meet datasheet specifications until power is removed. To trigger this condition, V_{BUS} must be driven from 5V to GND with a high slew rate. Achieving this slew rate requires a 0Ω short to the USB cable less than 10cm from the connector.



Charge Mode Battery Detection & Protection

VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents V_{BAT} from overshooting the OREG voltage when the battery is removed. If the VBAT Pin voltage is higher than 4.8V, the IC sets the FAULT bits to 100, sets the STAT bits to 11, and pulses the STAT pin.

Battery Detection During Charging

The IC can detect the presence, absence. During normal charging, once VBAT is close to VOREG and the termination charging, once VBAT is close to VOREG and the termination charge current is detected, the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current, IDETECT, for tDETECT. If VBAT is still above 2V, the battery is present and the IC sets the FAULT bits to 000. If VBAT is below 2V, the battery is absent and the IC:

- 1. Operation with No Battery
- 2. Sets the FAULT bits to 111.

Battery Short-Circuit Protection

If the battery voltage is below the short-circuit threshold (V_{SHORT}); a linear current source, I_{SHORT} , supplies V_{BAT} until V_{BAT} > V_{SHORT} .

System Operation with No Battery

The DIO59020 continues charging after VBUS POR with the default parameters and 500mA input current limit, regulating the V_{BAT} line to 3.78V (if set V_{OREG} at 4.2V). In this way, the DIO59020 can start the system without a battery. Re-connect power to VBUS or reset DISABLE pin, IC can exit No Battery Mode.

Charger Status/Fault Status

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt driven systems.

Table 8. STAT Pin Function

EN_STAT	Charge State	STAT Pin
X	No Charging	OPEN
1	Charging	LOW
х	Fault	2Hz Pulse

The FAULT bits (Reg0[2:0]) indicate the type of fault in Charge Mode (see Table 9).



Table 9. Fault Status Bits During Charge Mode

F	Fault Bit		Foult Description	
B2	B1	В0	Fault Description	
0	0	0	Normal (No Fault)	
0	0	1	VBUS OVP	
0	1	0	Sleep Mode	
0	1	1	Poor Input Source	
1	0	0	Battery OVP	
1	0	1	Thermal Shutdown	
1	1	0	N.A	
1	1	1	No Battery	

Charge Mode Control Bits

Setting either HZ_MODE or CE through I²C disables the charger and puts the IC into High-Impedance Mode.

Table 10. DISABLE Pin and CE Bit Functionality

Charging	DISABLE Pin	CE	HZ_MODE
ENABLE	0	0	0
DISABLE	X	1	X
DISABLE	X	Х	1
DISABLE	1	Х	Х

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the FAULT state define the operational mode of the charger.

Table 11. Operation Mode Control

HZ_MODE	OPA_MODE	Operation Mode	
0	0	0	Charge
0	X	1	No charging
0	1	0	Boost
1	X	Х	High Impedance

Boost Mode

Boost Mode can be enabled if OTG pin and OPA_MODE bits as indicated in Table 12 The OTG pin ACTIVE state is 1 if OTG_PL=1 and 0 when OTG_PL=0.

If boost is active using the OTG pin, Boost Mode is initiated even if the HZ_MODE=1. The HZ_MODE bit overrides the OPA_MODE bit.

Table 12. Enabling Boost

OTG_EN	OTG Pin	HZ_MODE	OPA_MODE	BOOST
1	ACTIVE	X	X	Enabled
Х	X 0		1	Enabled
Х	ACTIVE	X	0	Disabled
0	X	1	Х	Disabled
1	ACTIVE	1	1	Disabled
0	ACTIVE	0	0	Disabled



Boost COT Control

The IC uses a constant on-time and valley current detect to regulate VBUS. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During COT Mode, the output voltage drops slightly as the input current rises.

PFM Mode

If VBUS>VREF_{BOOST} (nominally 5.05V) when the valley current comes to 0, the regulator enters PFM Mode. Boost pulses are inhibited until V_{BUS} <VREF_{BOOST}. Once V_{BUS} <VREF_{BOOST}, boost pulses are allowed for one or several times until V_{BUS} >VREF_{BOOST}. Therefore the regulator behaves like a burst mode regulator, with the average of its output voltage ripple at 5.05V in PFM Mode.

Table 13. Boost PWM Operating States

Mode	Description	Invoked When		
LIN	Linear Startup	V _{BAT} >V _{BUS}		
SS	Boost Soft-Start	V _{BUS} <v<sub>BST</v<sub>		
DOT	Deart Operation Made	V _{BAT} >UVLO _{BST} and SS		
BST	Boost Operation Mode	Completed		

Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS} , as well as reverse flow from V_{BAT} .

LIN State

When EN rises, if V_{BAT} >UVLO_{BST}, the regulator attempts to bring PMID within 200mV of VBAT using an internal 800mA current source from VBAT (LIN State). If PMID has not achieved V_{BAT} - 200mV after 500 μ s, a FAULT state is initiated.

SS State

When PMID> V_{BAT} -200mV, the boost regulator begins switching with a SS modulator. The output slews up slowly and smoothly until V_{BUS} = $V_{REF_{BOOST}}$.

If the output fails to achieve set point (VBST) within SS time, normally 128µs, a fault state is initiated.

BST State

This is the normal operating mode of the regulator. The regulator uses a constant on-time and valley current detect modulation scheme. The minimum t_{ON} is proportional to $\frac{V_{OUT} - V_{IN}}{V_{OUT}}$, which keeps the regulator's switching frequency reasonably constant in CCM.

To ensure the VBUS does not pump significantly above the regulation point, the boost switch remains off as long as FB>V_{REF}.

Boost Faults

If a Boost FAULT OCCURS:

- OPA MODE bit is reset.
- The power stage is in High-Impedance Mode.



3. The FAULT bits (REG0[2:0]) are set per Table 14.

Restart After Boost Faults

If boost was enabled with the OPA_MODE bit and OTG_EN=0, Boost Mode can only be enabled through subsequent I²C commands since OPA_MODE is reset on boost faults. If OTG_EN=1 and the OTG pin is still ACTIVE (see Table 12), the boost restarts after a 10ms delay, as shown in Figure 10. If the fault condition persists, restart is attempted every 10ms until the fault clears or an I²C command disables the boost.

	Table 14. Fault bits burning boost wode				
F	Fault Bit		Fault Description		
B2	B1	В0	rauit Description		
0	0	0	Normal (no fault)		
0	0	1	V _{BUS} >VBUS _{OVP}		
0	1	0	VBUS fails to achieve the voltage required to advance to the next state during soft-start or sustained (>50µs) current limit during the BST state.		
0	1	1	N/A: This code does not appear.		
1	0	0	N/A: This code does not appear.		
1	0	1	Thermal shutdown		
1	1	0	N/A: This code does not appear.		
1	1	1	N/A: This code does not appear.		

Table 14. Fault Bits During Boost Mode

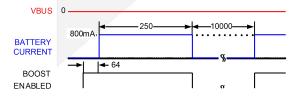


Figure 10. Boost Response Attempting to Start into VBUS Short Circuit (Times in μs)

Monitor Register (Reg10H)

Additional status monitoring bits enable the host processor to have more visibility into the status of the IC. The monitor bits are real-time status indicators.

I²C Interface

The DIO59020's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I²C-Bus specifications. The SCL line is an input and the SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 15. I²C Slave Address Byte

Part Type	7	6	5	4	3	2	1	0
DIO59020	1	1	0	1	0	1	0	R/W



In hex notation, the slave address assumes a 0LSB. The hex slave address for the DIO59020 is D4H and is D6H for all other parts in the family.

Bus Timing

As shown in Figure 11, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

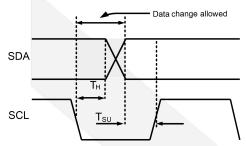
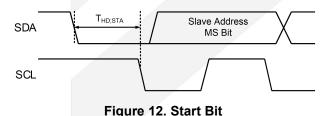


Figure 11. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH.A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 12.



A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 13.

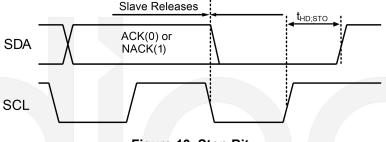


Figure 13. Stop Bit

During a read from the DIO 59020 (Figure 15, Figure 16), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0 transition on SDA while SCL is HIGH, as shown in Figure 14.

High-Speed (HS) Mode

The protocols for High-Speed(HS), Low-Speed(LS), and Fast-Speed(FS) Modes are identical except the bus speed for HS Mode is 3.4MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a start condition. The master code is sent in Fast or Fast Plus Mode (less than1MHz clock); slaves do not



ACK this transmission.

The master then generates a repeated start condition (Figure 14) that causes all slaves on the bus to switch to HS Mode. The master then sends I²C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a stop bit (Figure 13) is sent by the master. While in HS Mode, packets are separated by repeated start conditions (Figure 14).

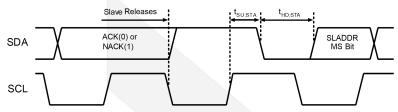


Figure 14. Repeated Start Timing

Read and Write Transactions

The figure below outline the sequences for data read and write. Bus control is signified by the shading of the

packet, defined as

Master Drives Bus and Slave Drive Bus

. All addresses and data are MSB first.

Table 15. Bit Definitions for Figure 15, Figure 16

Symbol	Definition										
S	START, see Figure 12										
А	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.										
Ā	NACK. The slave sends a 1 to NACK the preceding packet.										
R	Repeated START, see Figure 14										
Р	STOP, see Figure 13.										

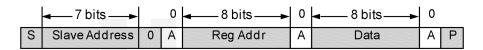


Figure 15. Write Transaction



Figure 16. Read Transaction



Register Bit Definitions

1 CONTROL0 Register (0x00) Default Value=X1XX0XXX

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME	Reserved	EN_STAT	S.	ГАТ	BOOST	FAULT			
R/W	R/W	R/W		R	R	R			
Function	R/W Unused	R/W 0: Prevents STAT pin from going LOW during charging; STAT pin still pulses to enunciate faults 1: Enables STAT pin LOW when IC is charging.	00 :Re 01 : C in pro	eady harge gress harge	R 0: IC is not in Boost Mode 1:IC is in Boost Mode	required to adv soft-start or sus during the BST 011 = N/A: This 100 = N/A: This 101 = Thermal	de: No Fault) VP ode ut Source OVP Shutdown ery e: no fault) /BUS _{OVP} ils to achieve the rance to the next stained (>50µs) constate. s code does not a shutdown	state during urrent limit uppear. uppear.	
							s code does not a	• •	

2 CONTROL1 Register (0x01) Default Value=0111 0000 (70h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{INLIM}		Reserved		TE	CE	HZ_MODE	OPA_MODE
R/W	R/W R/W		R/W	R/W	R/W	R/W		
	Input current Unused		0: Disable charge current	0: Charger	0: Not High-Impedance	0: Charge		
	limit:		termination. enabled.		Mode.	Mode.		
Function	00:100 m	nΑ			1: Enable charge current 1: Charger		1: High-Impedance	1: Boost Mode.
runction	01 :500 r	mA		/	termination.	disabled.	Mode.	
	10 :800 r	10 :800 mA		-i				
	11: No lir	mit						



3 OREG Register (0x02) Default Value=0000 1010 (0Ah)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME			OR	EG	OTG_PL OTG_EN			
R/W			R	W		R/W R/W		
	Charger o	utput "float"	voltage;				0: OTG pin active LOW.	0:
Function	programm	able from 4	.2 to 4.4V; d	defaults to 0	1: OTG pin active HIGH.	Disables OTG pin.		
Function	00 0000~	10 0011 : 4.	2V; 10 0°	100~10 100		1: Enables OTG pin.		
	10 1001~1	0 1011: 4.3	5V; 10 1	100~11 111				

4 IC_INFO Register (0x03) Default Value=1001 0100 (94h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1 Bit 0			
NAME	F	Reserved			PI	l	REV			
R/W				R		R				
Function	Identifies the I	C supplier.		Part num	nber bits.		IC Revision, revision 1.X, where X is the decimal of these three bits.			

Bit	Bit 7	Bit 6 Bit 5		Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME	Reserved		V(I _{OCHARGE})		Reserved	V(I _{TERM})			
R/W	R/W		R/W		R/W	R/W			
	0 =	Programs the m	naximum charge o	current	Unused	Sets the current	t used for chargi	ng termination	
	Unused	000: 37.5mV;	001: 44.4mV;			000 : 3.1mV;	001: 6.3mV;		
		010: 51.2 mV;	011: 57.5 mV;			010: 9.4mV;	011: 12.5mV;		
Function		100: 71.3 mV;	101: 78.1 mV;			100: 15.6mV;	101: 18.8mV;		
runction		110: 91.9 mV;	111: 101.8 m\	/ ;		110: 21.9mV;	111: 25mV;		
		The charge curre	nt step (I _{OCHARGE})	is calculated	The termination current step (I _{TERM}) can be calculated using:				
		using:							
		I _{OCHARGE} = V(I	OCHARGE)/RSENSE;			I _{TERM} = V(I _{TERM})/ R _{SENSE} ;			

6 SP_CHARGER Register (0x05) Default Value=011X X100

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserve	Reserve	Reserve	SP	EN_LEVEL	VSP		
R/W	R/W	R/W	R/W	R	R	R/W		
	Unused	Unused	Unused	0: Special charger is not	0: DISABLE pin	Special ch	arger inpu	t
				active (V _{BUS} is able to stay	is LOW.	regulation	voltage	
				above V _{SP}).	1: DISABLE pin	000: 4.225	5V; 001: 4.	300V;
Function				1: Special charger has	is HIGH.	010: 4.375	5V; 011: 4.	450V;
				been detected and V _{BUS} is		100: 4.525	5V; 101: 4.	600V;
				being regulated to V _{SP} .		110: 4.675V; 111: 4.750V		750V



7 Register (0x07) Default Value=0000 0001 (01h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME		Reserved		Reserved	Rese	rved	V _{RCH}		
R/W	R/W			R/W	R/	W	R/W		
		Unused		Unused	Unu	sed	Recharge voltage	e of V _{OREG} drops.	
Function							00: 50mV; 01: 100mV;		
							10: 150mV; 11: 200mV		

8 MONITOR Register (0x10h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{TERM_CMP}	V _{BAT_CMP}	LINCHG	T_100	Існв	I _{BUS}	VBUS_VALID	cv
R/W	R	R	R	R	R	R	R	R

Function

ITERM CMP:

ITERM comparator output. 0: Vcsin-Vbat<Viterm. 1: Vcsin-Vbat>Viterm

V_{BAT CMP}

Output of VBAT comparator in charging mode, 0: $V_{BAT} < V_{SHORT}$ 1: $V_{BAT} > V_{SHORT}$

LINCHG

In charging mode, 0: 30mA linear charger Not Enable; 1: 30mA linear charger Enable.

T_100

Thermal comparator $0: T_J < 100^{\circ}C; 1: T_J > 100^{\circ}C$

ICHG

In charging mode, 0: Charging Current Controlled by I_{CHARGE} Control Loop .1: Charging Current Not Controlled by I_{CHARGE} Control Loop.

IRUS

In charging mode, 0: I_{BUS} Limiting Charging Current. 1: Charge Current Not Limited by I_{BUS}

V_{BUS_VALID}

When V_{BUS}>V_{BAT},0:V_{BUS} Not Valid 1: V_{BUS} is Valid

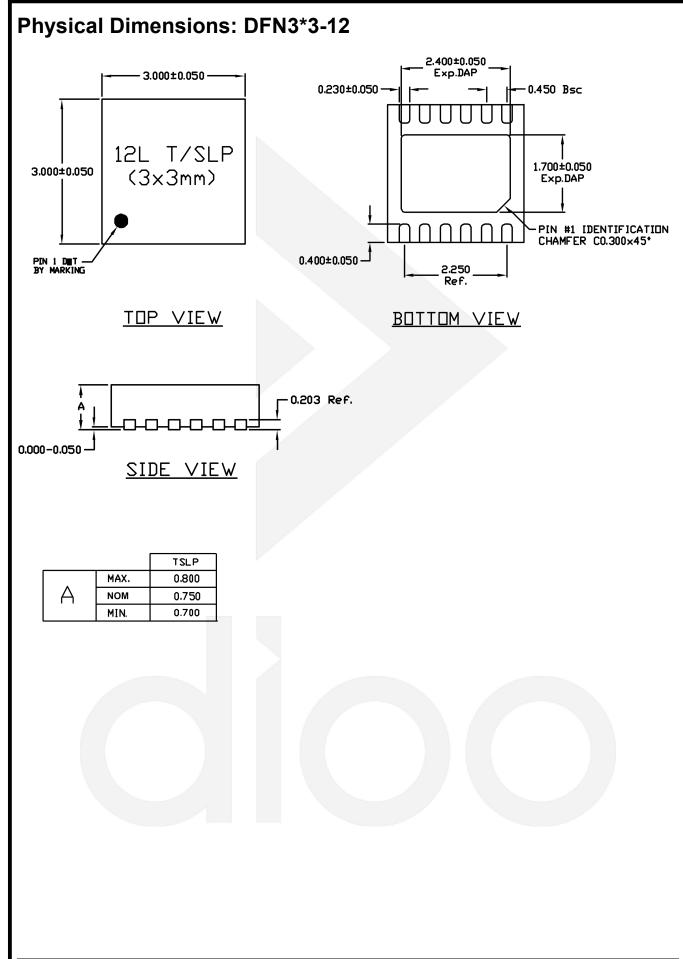
CV

In charging mode. 0: Constant Current Charging. 1: Constant Voltage Charging.

PCB Layout Recommendations

Bypass capacitors should be placed as close to the IC as possible. In particular, the total loop length for CMID should be minimized to reduce overshoot and ringing on the SW, PMID, and VBUS pins. All power and ground pins must be routed to their bypass capacitors, using top copper whenever possible. Copper area connecting to the IC should be maximized to improve thermal performance if possible.







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